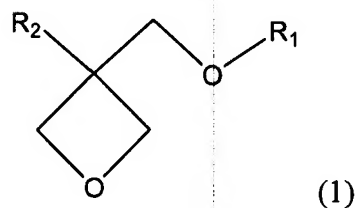


**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. **(Currently amended ):** A radiation curable resin composition comprising:
- a polyfunctional epoxy polymer (Component A) having a polybutadiene skeleton or a hydrogenated polybutadiene skeleton and two or more glycidyloxy groups in the molecule;
- an oxetane compound (Component B) represented by Formula (1) below and/or a compound in which an optionally branched alkyl group having 8 to 30 carbons has one epoxy group ~~monofunctional epoxy compound~~ (Component C) having 8 to 30 carbons; and
- a cationic photopolymerization initiator (Component X),
- wherein a number of parts of Component A added is 25 to 45 parts by weight relative to 100 parts by weight of the total resin components



wherein R<sub>1</sub> denotes an optionally branched alkyl group having 6 to 30 carbons, or a phenyl group substituted with an alkyl group having 4 to 30 carbons, and R<sub>2</sub> denotes a hydrogen atom or an optionally branched alkyl group having 1 to 6 carbons.

2. **(Original):** The radiation curable resin composition according to Claim 1, wherein a polyfunctional epoxy compound other than Component A and/or a polyfunctional oxetane compound are not contained at 10 parts or greater relative to 100 parts of the total resin components.

3. **(Withdrawn):** The radiation curable resin composition according to Claim 1, wherein the composition comprises a polymer having a glass transition temperature of -30°C or lower (Component D).

4. **(Withdrawn):** The radiation curable resin composition according to Claim 3, wherein the polymer (Component D) is a polybutadiene or polyisoprene to which 1 to 20 molecules of maleic anhydride are added per polymer molecule, or one obtained by ring-opening these acid anhydrides with an alcohol

5. **(Original):** The radiation curable resin composition according to any one of Claims 1 to 4, wherein the composition further comprises an antioxidant.

6. **(Withdrawn):** The radiation curable resin composition according to any one of Claims 1 to 4, wherein the composition further comprises an inorganic ion-exchanger.

7. **(Withdrawn):** The radiation curable resin composition according to any one of Claims 1 to 4, wherein the composition further comprises an antioxidant and an inorganic ion-exchanger.

8. **(Original):** A cured material formed by curing the radiation curable resin composition according to any one of Claims 1 to 4 by irradiation with actinic radiation.

9. **(Original):** A cured material formed by curing the radiation curable resin composition according to Claim 5 by irradiation with actinic radiation.

**10. (Withdrawn):** A cured material formed by curing the radiation curable resin composition according to Claim 6 by irradiation with actinic radiation.

**11. (Withdrawn):** A cured material formed by curing the radiation curable resin composition according to Claim 7 by irradiation with actinic radiation.

**12. (Original):** The cured material according to Claim 8, wherein the cured material has a storage modulus ( $G'$ ) of  $1.2 \times 10^5$  Pa or less and a  $\tan \delta$  of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.

**13. (Original):** The cured material according to Claim 9, wherein the cured material has a storage modulus ( $G'$ ) of  $1.2 \times 10^5$  Pa or less and a  $\tan \delta$  of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.

**14. (Original):** The cured material according to Claim 10, wherein the cured material has a storage modulus ( $G'$ ) of  $1.2 \times 10^5$  Pa or less and a  $\tan \delta$  of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.

**15. (Original):** The cured material according to Claim 11, wherein the cured material has a storage modulus ( $G'$ ) of  $1.2 \times 10^5$  Pa or less and a  $\tan \delta$  of 0.14 or less in a dynamic viscoelasticity measurement at 25°C and 1 Hz.